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PD\_FB\_01

-METRIC-

ISO-Projektion  
 Methode 1

1 2 3 4

A A

B B

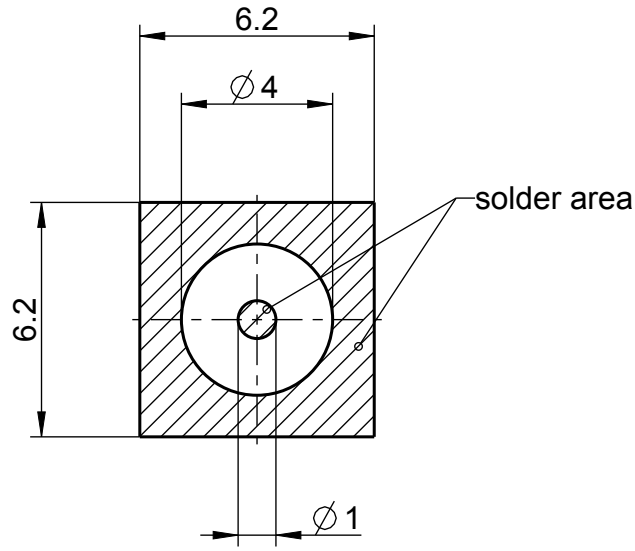
C C

D D

E E

F F

Leiterplatten-Layout  
 PCB layout  
 B 178a



A wide variety of transmissionline topologies and pcb-parameters like permittivity, substrate thickness, and board-stackup are applied by customers. These parameters have a strong impact on the high frequency performance of the mounted connector.  
 Please note, that the given layout is not optimised to fit all of the possible board configurations regarding RF-performance, it represents a recommendation for optimum solderability of the connector.  
 In order to guarantee optimum high frequency properties of the connector, an RF-analysis of the connector to board transition is recommended.

<b>Rosenberger</b>		general tolerance		scale: 5:1	weight[g]:
		ISO 2768	RN 006-01	material:	
vertraulich / confidential		mH	dimensions <0,5 and symmetry	title:	
		date	name	Leiterplatten-Layout PCB layout	
		drawn	12.12.2007 S_Huber-Sieg		
		check.	25.11.2016 J_Krautenbac		
		appr.	25.11.2016 J_Krautenbac	drawing-no.: MB_178A	
dimensioning incl. plating				sheet: 1	
a01	16-0057	A_Nobis	24.11.2016	of: 1	
a00	07-s517	S_Huber-Sieg	12.12.2007	remarks: .	
rev.	change-no	name	date		

1 2 3 4